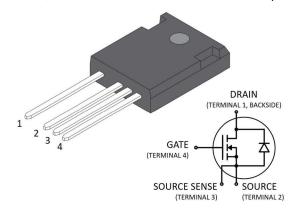


3300 V, 80 mΩ SiC N-Channel Power MOSFET

Product Overview

The silicon carbide (SiC) power MOSFET product line from Microchip increases the performance over silicon MOSFET and silicon IGBT solutions while lowering the total cost of ownership for high-voltage applications. The MSC080SMA330B4 device is a 3300 V, 80 m Ω SiC MOSFET in a TO-247 4-lead package with a source sense.



Features

The following are key features of the MSC080SMA330B4 device:

- Low capacitances and low gate charge
- · Fast switching speed due to low internal gate resistance (ESR)
- Stable operation at high junction temperature, T_{J(max)} = 150 °C
- Fast and reliable body diode
- Superior avalanche ruggedness
- RoHS compliant

Benefits

The following are benefits of the MSC080SMA330B4 device:

- High efficiency to enable lighter, more compact system
- · Simple to drive and easy to parallel
- Improved thermal capabilities and lower switching losses
- Eliminates the need for external freewheeling diode
- · Lower system cost of ownership

Applications

The MSC080SMA330B4 device is designed for the following applications:

- · PV inverter, converter, and industrial motor drives
- Smart grid transmission and distribution
- Induction heating and welding
- H/EV powertrain and EV charger
- Power supply and distribution

1. Device Specifications

This section shows the specifications of the MSC080SMA330B4 device.

1.1 Absolute Maximum Ratings

The following table shows the absolute maximum ratings of the MSC080SMA330B4 device.

Symbol	Parameter	Ratings	Unit
V _{DSS}	Drain source voltage	3300	V
I _D	Continuous drain current at T_C = 25 °C	41	A
	Continuous drain current at T_C = 100 °C	26	
I _{DM}	Pulsed drain current ¹	100	
V _{GS}	Gate-source voltage	23 to -10	V
PD	Total power dissipation at T_C = 25 °C	381	W
	Linear derating factor	3.04	W/°C

Table 1-1. Absolute Maximum Ratings

Note:

1. Repetitive rating: pulse width and case temperature limited by maximum junction temperature.

The following table shows the thermal and mechanical characteristics of the MSC080SMA330B4 device.

 Table 1-2. Thermal and Mechanical Characteristics

Symbol	Characteristic/Test Conditions	Min	Тур	Max	Unit
R _{θJC}	Junction-to-case thermal resistance		0.22	0.33	°C/W
TJ	Operating junction temperature	-55		150	°C
T _{STG}	Storage temperature	-55		150	°C
TL	Soldering temperature for 10 seconds (1.6 mm from case)			300	°C
	Mounting torque, 6-32 or M3 screw			10	lbf-in
				1.1	N-m
Wt	Package weight		0.22		oz
			6.2		g

1.2 Electrical Performance

The following table shows the static characteristics of the MSC080SMA330B4 device. T_J = 25 $^{\circ}$ C unless otherwise specified.

Table 1-3. Static Characteristics

Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	V_{GS} = 0 V, I _D = 100 µA	3300			V
R _{DS(on)}	Drain-source on resistance ¹	V_{GS} = 20 V, I _D = 30 A		84	105	mΩ

Device Specifications

cor	tinued					
Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
V _{GS(th)}	Gate-source threshold voltage	$V_{GS} = V_{DS}, I_D = 3 \text{ mA}$	1.9	2.97		V
I _{DSS}	Zero gate voltage drain current	V_{DS} = 1200 V, V_{GS} = 0 V			100	μA
		V _{DS} = 1200 V, V _{GS} = 0 V, T _J = 125 °C			500	
I _{GSS}	Gate-source leakage current	V _{GS} = 20 V/–10 V			±100	nA

Note:

1. Pulse test: pulse width < 380 μ s, duty cycle < 2%.

The following table shows the dynamic characteristics of the MSC080SMA330B4 device. T_J = 25 $^{\circ}$ C unless otherwise specified.

Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
C _{iss}	Input capacitance	$V_{GS} = 0 V$		3462		pF
C _{rss}	Reverse transfer capacitance	V _{DD} = 2400 V V _{AC} = 25 mV		4		
C _{oss}	Output capacitance	f = 200 kHz		77		
Qg	Total gate charge	$V_{GS} = -5 V/20 V$ $V_{DD} = 2650 V$		55		nC
Q _{gs}	Gate-source charge			51		
Q _{gd}	Gate-drain charge	I _D = 30 A		161		
t _{d(on)}	Turn-on delay time	V _{DD} = 2310 V		34		ns
t _r	Voltage rise time	$V_{GS} = -5 V/20 V$		25		
t _{d(off)}	Turn-off delay time	$I_{\rm D} = 20 {\rm A}$		50		
t _f	Voltage fall time	$R_{g(ext)} = 8 \Omega$ Freewheeling diode =		32		
Eon	Turn-on switching energy	MSC080SMA330B4 (V _{GS} = -5		1590		μJ
E _{off}	Turn-off switching energy	V) (reference Fig. 1-20)		450		
t _{d(on)}	Turn-on delay time	V _{DD} = 2310 V		35		ns
t _r	Voltage rise time	$V_{GS} = -5 V/20 V$		18		
t _{d(off)}	Turn-off delay time	I _D = 20 A		50		
t _f	Voltage fall time	$R_{g(ext)} = 8 \Omega$		22		
Eon	Turn-on switching energy	Freewheeling diode = MSC030SDA330B (reference		1300		μJ
E _{off}	Turn-off switching energy	Fig. 1-20)		360		
ESR	Gate equivalent series resistance	f = 1 MHz, 25 mV, drain short		3.7		Ω
E _{AS}	Avalanche energy, single pulse	V _{DS} = 150 V, I _D = 30 A		100		mJ

Table 1-4. Dynamic Characteristics

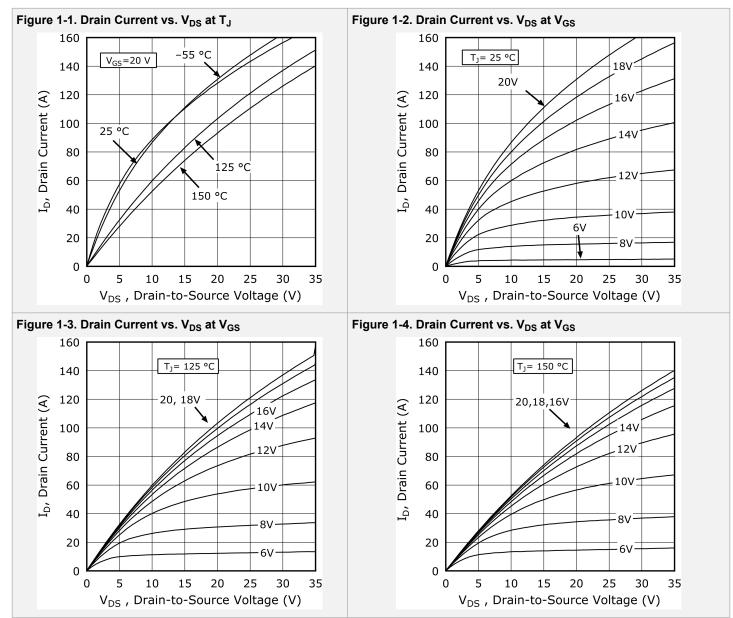
The following table shows the body diode characteristics of the MSC080SMA330B4 device. T_J = 25 $^{\circ}$ C unless otherwise specified.

	Body Diode Characteristics	
Symbol	Characteristic	Tost Condition

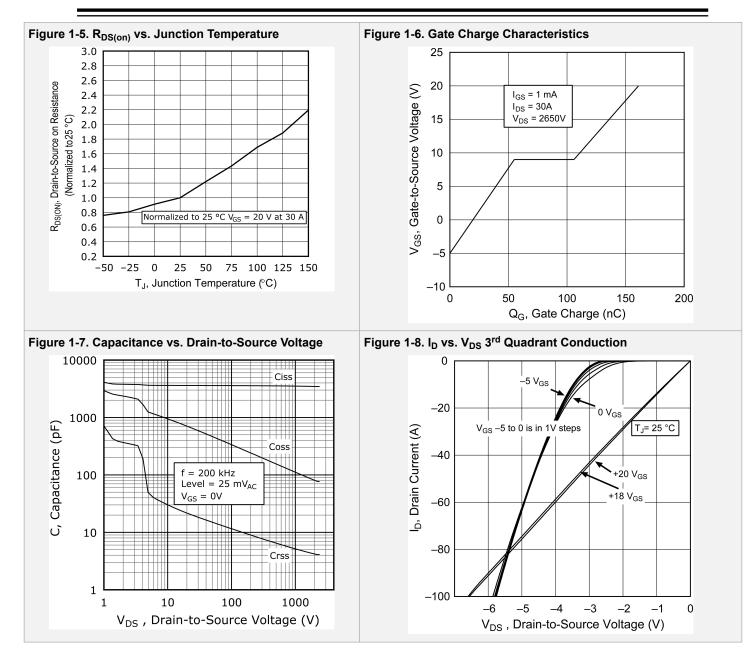
Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
V _{SD}	Diode forward voltage	I_{SD} = 30 A, V_{GS} = 0 V		4.0		V
		I_{SD} = 30 A, V_{GS} = –5 V		4.2		
t _{rr}	Reverse recovery time	I_{SD} = 20 A, V_{GS} = -5 V, Drive		35		ns
Q _{rr}	Reverse recovery charge	Rg = 8 Ω, V _{DD} = 2310 V, dl/dt = –3760 A/μs		818		nC
I _{RRM}	Reverse recovery current			41		А

1.3 Typical Performance Curves

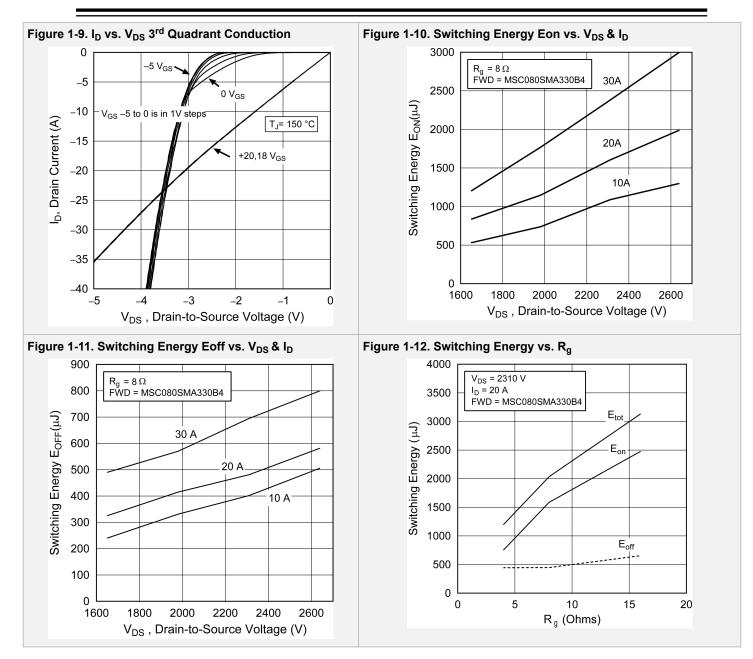
This section shows the typical performance curves of the MSC080SMA330B4 device.



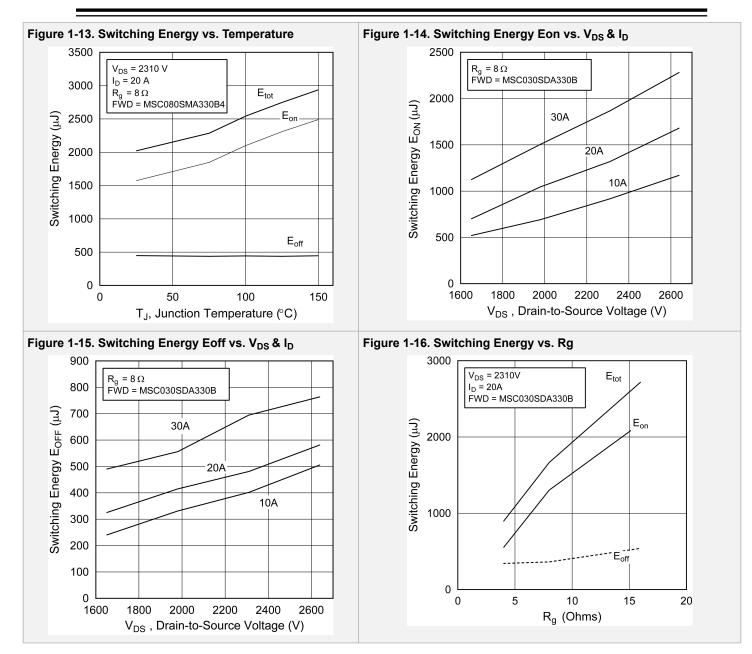
Device Specifications



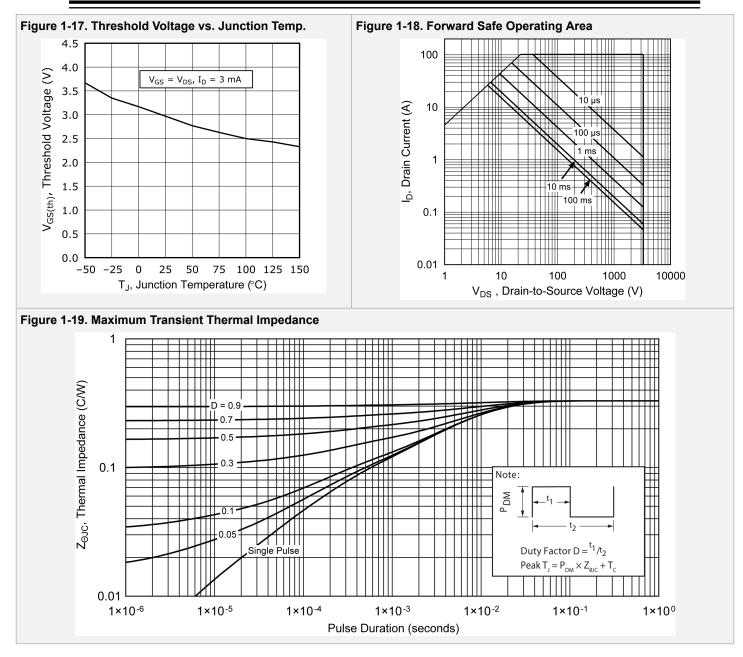
Device Specifications



Device Specifications

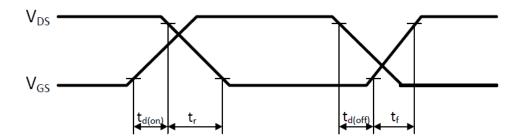


Device Specifications



The following figure shows the switching waveform diagram of the MSC080SMA330B4 device.

Figure 1-20. Switching Waveform



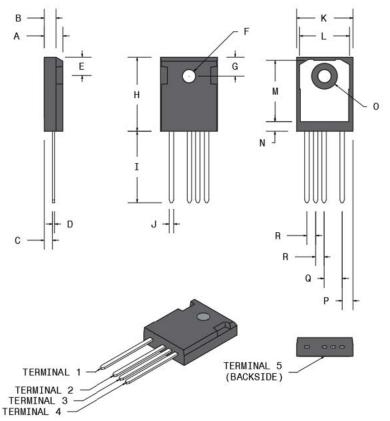
2. Package Specification

This section shows the package specification of the MSC080SMA330B4 device.

2.1 Package Outline Drawing

The following figure illustrates the TO-247-4L package outline of the MSC080SMA330B4 device.

Figure 2-1. Package Outline Drawing



The following table shows the TO-247-4L dimensions and should be used in conjunction with the package outline drawing.

Symbol	Min (mm)	Max (mm)	Min (in.)	Max (in.)
A	4.90	5.17	0.193	0.204
В	1.85	2.11	0.073	0.083
С	2.25	2.51	0.089	0.099
D	0.55	0.68	0.022	0.027
E	5.49	5.74	0.216	0.226
F	3.56	3.66	0.140	0.144
G	6.15 BSC		0.242 BSC	
Н	20.83	21.08	0.820	0.830

Package Specification

continued				
Symbol	Min (mm)	Max (mm)	Min (in.)	Max (in.)
I	19.81	20.32	0.780	0.800
J	1.07	1.33	0.042	0.052
К	15.77	16.03	0.621	0.631
L	13.89	14.15	0.547	0.557
Μ	16.25	16.85	0.640	0.663
Ν	2.00	2.75	0.079	0.108
0	7.10	7.50	0.280	0.295
Р	2.87 BSC		0.113 BSC	
Q	5.08 BSC		0.200 BSC	
R	2.54 BSC		0.100 BSC	
Terminal 1	Drain			
Terminal 2	Source			
Terminal 3	Source sense			
Terminal 4	Gate			
Terminal 5	Drain			

3. Revision History

Table 3-1. Revision History

Revision	Date	Description
А	01/2022	Document created.

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